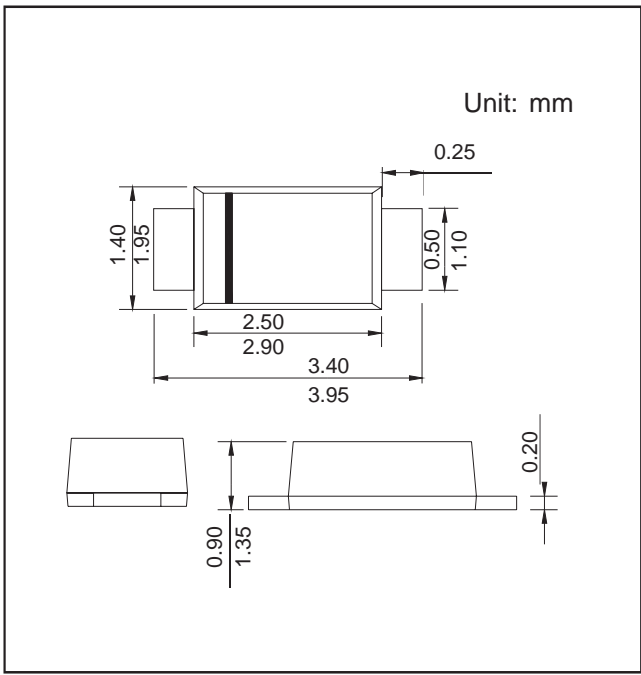


62')/

For surface mounted application
 Glass passivated device
 Low forward voltage drop
 High current capability
 Easy pick and place

Plastic material used carriers Underwriters
 Laboratory Classification 94V-O
 High temperature soldering guaranteed:
 250 C/10 seconds

Case : JEDEC SOD-123FL molded plastic bodyover
 passivated chip
 Terminals: Plated axial leads, solderable per MIL-STD-750, Method 2026
 Polarity: Color band denotes cathode end Mounting
 Position: Any



@ 25°C Ambient Temperature (unless otherwise noted)

Parameter	Symbols	A1	A2	A3	A4	A5	A6	A7	Units
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	Volts
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	Volts
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	Volts
Maximum average Forward Rectified Current 0.375" (9.5mm) length at $T_J = 75^\circ C$	$I_{(AV)}$	1.0							Amp
Peak Forward Surge Current (8.3ms half sine-wave superimposed on rated load) (JEDEC method) at $T_J = 75^\circ C$	I_{FSM}	30.0							Amps
Maximum Instantaneous Forward Voltage at 1A0	V_F	1.0							Volts
Maximum Reverse current at rated DC Voltage $T_J = 25^\circ C$ $T = 100^\circ C$	I_R	5.0							μA
		50.0							
Typical Thermal resistance (Note 2)	$R_{\theta JA}$	65.0							$^\circ C/W$
Typical Junction Capacitance (Note 1)	C_j	10.0							pF
Maximum DC Blocking Voltage	T_A	+150							$^\circ C$
Operating and Storage temperature range	T_J	-55 to +150							$^\circ C$
	T_{STG}								

Note 1: Measured at 1MHz and applied reverse voltage of 4.0V DC.
 2. Thermal resistance from junction to ambient at 0.375" (9.5mm) height,
 P.C. mounted

